

CHIP PACKAGE WITH MULTIPLE CHIPS CONNECTED BY BUMPS

Appl. No. : 10/695,630 Confirmation No. 5386
Applicant : Shih-Hsiung Lin,
Mou-Shiung Lin
Filed : October 27, 2003
TC/A.U. : 2826
Examiner : WILLIAMS, ALEXANDER O
Docket No. : MEGP0005USA4
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

Sir:

- 5 In response to the Office action of November 06, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 13 of this paper.